



# Thermal Clay

## Product Description

MT05 series thermal clay, with very low thermal resistance, can be deformed without any tools or fixtures and can be easily applied to uneven interstices or winding without dripping.

## Features

- Great heat dissipation.
- low thermal resistance.
- Highly deformable.
- Excellent gap filling.



## Applications

- Semi-conductor and heat sink.
- Power resistor.
- Temperature regulator.
- Thermoelectric cooler.
- CPU and graphics card processor.

## Storage and Shelf Life

- Store in original cartons at 23±5°C and 60%±10% relative humidity in order to obtain best.
- Performance, besides use these products within 15 months from date of manufacture.



## SPECIFICATION

Physical Properties	Unit	SF-GE30TCC-MT05	Test Method
Color	—	Dark green	—
Hardness	Shore A	25	—
Specific Gravity	g/cm <sup>3</sup>	2.6	ASTM D792
Voltage Breakdown	Kv	>3	—
Flammability Class	UL94	V-0	—
Thermal Conductivity	w/m-k	>3	ASTM D5470
Volume resistivity	Ω.cm	10 <sup>13</sup>	ASTM D257
Surface resistance	Ω	10 <sup>15</sup>	ASTM D257